

	SPECIFICATIONS	
CUSTOMER	:	
SAMPLE CODE	SH480272T0	005-IHC03
MASS PRODUCTION CODE	PH480272T0	005-IHC03
SAMPLE VERSION	. 01	
SPECIFICATIONS EDITION	001	
DRAWING NO. (Ver.)	LMD-PH480	272T005-IHC03 (Ver.001)
PACKAGING NO. (Ver.)	:	
		Date:
Approved	Checked	Date: Designer
Approved 黃秋源 Oliver Huang	Checked 石建莊 Stone Shin	
黄秋源	石建莊 Stone Shin	Designer 王聖硯
黄秋源 Oliver Huang  ■ Preliminary specification □ Specification for sample	石建莊 Stone Shin	Designer 王聖硯 Stephen Wang



# History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
12/18/2017	01	001	New Drawing	-	Stephen
				Т	otal: 29 Page



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# 1. SPECIFICATIONS

### 1.1 Features

Item	Standard Value
Display Resolution	480 *3 (RGB) * 272 Dots
LCD Type	a-Si TFT , Normally white , Transmissive type
Screen size(inch)	4.3 inch
Viewing Direction	6 O'clock
Color configuration	RGB - Strip
Weight	TBD g
Backlight Type	White LED B/L
Interface	HDMI Interface
Controller/Driver IC	HYCON 4635
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer website :
	http://www.powertip.com.tw/news_detail.php?Key=1&cID=1

# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	105.5 (W) * 67.2 (L) * 15.76 (H)	mm

#### LCD panel

Item	Standard Value	Unit
Active Area	95.04 (W) * 53.856 (L)	mm

#### Touch Panel

Item	Standard Value	Unit
Viewing Area	97.9 (W) * 56.2 (L)	mm

Note : For detailed information please refer to LCM drawing.



## 1.3 Absolute Maximum Ratings

#### Module

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply for Digital Circuit	VBus	GND=0V	-0.3	+6.0	V
Operating Temperature	Тор	-	-20	+70	°C
Storage Temperature	Тsт	-	-30	+80	℃

The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

# **1.4 DC Electrical Characteristics**

Module		GND = 0V, Ta = 25 %				D = 0V, Ta = 25 ℃
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Input Signal Voltage	VBus	4.5	5.0	5.5	V	Note
Supply Current	IVBus	TBD	TBD	TBD	mA	Pattern = Full Display

#### Note: Confirm the input current is greater than 1A.



# 1.5 Optical Characteristics

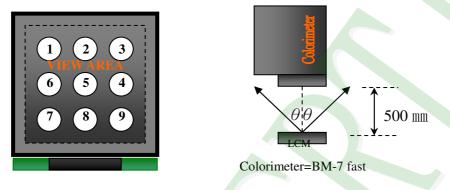
### TFT I CD Module

TFT LCD Module						Т	a=25℃	
ltem		Symbol	Condition	Min.	Тур.	Max.	unit	
Doopopoo Timo	Rise	Tr	Ta = 25 ℃	-	10	20	ma	Note 2
Response Time	Fall	Tf	$\theta X,  \theta Y = 0^{\circ}$	-	15	30	ms	Note 2
	Тор	θY+		-	60	-		
	Bottom	θY-	CR ≥ 10	-	60	-	Dog	Note 4
Viewing Angle	Left	θX-	UR 2 10	-	60	-	Deg.	Note 4
	Right	θX+		-	60	-		
Contrast Ratio	C	CR		500	600	-	-	Note 3
	White	Х		0.24	0.29	0.34		
	vvnite	Y	-	0.26	0.31	0.36		Note1
	Dud	Х		0.52	0.57	0.62		
Color of CIE Coordinate	Red	Y	Ta = 25 ℃ θX , θY = 0°	0.28	0.33	0.38		
(With B/L)	Green	Х	0, 01 = 0	0.30	0.35	0.40		
	Green	Y		0.56	0.61	0.66		
	Blue	Х		0.10	0.15	0.20		
	Diue	Y		0.00	0.07	0.12		
Average Brightn	ess							
Pattern=White Dis	splay	IV		(680)	(850)		cd/m <sup>2</sup>	Note1
(With LCD)*1		IV	VBus=5.0V	(000)	(850)	-	Cu/III	NOLET
, , , , , , , , , , , , , , , , , , ,			PWM="High"					
Uniformity			(Duty=100%)					
(With LCD)	*2	∆B		70	-	-	%	Note1



Note 1:

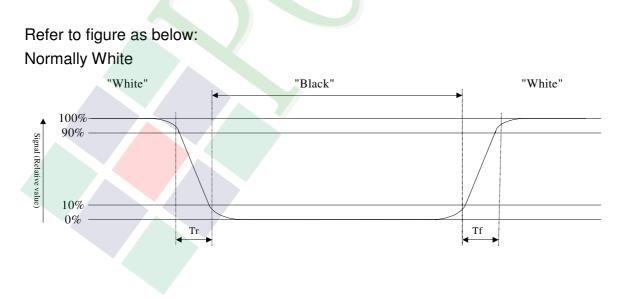
- \*1 : △B=B(min) / B(max) \* 100%
- \*2 : Measurement Condition for Optical Characteristics:
  - a : Environment: 25°C ±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance: 500  $\pm$  50  $\,{\rm mm}^{-}$  , (0= 0 °)
  - c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%



To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

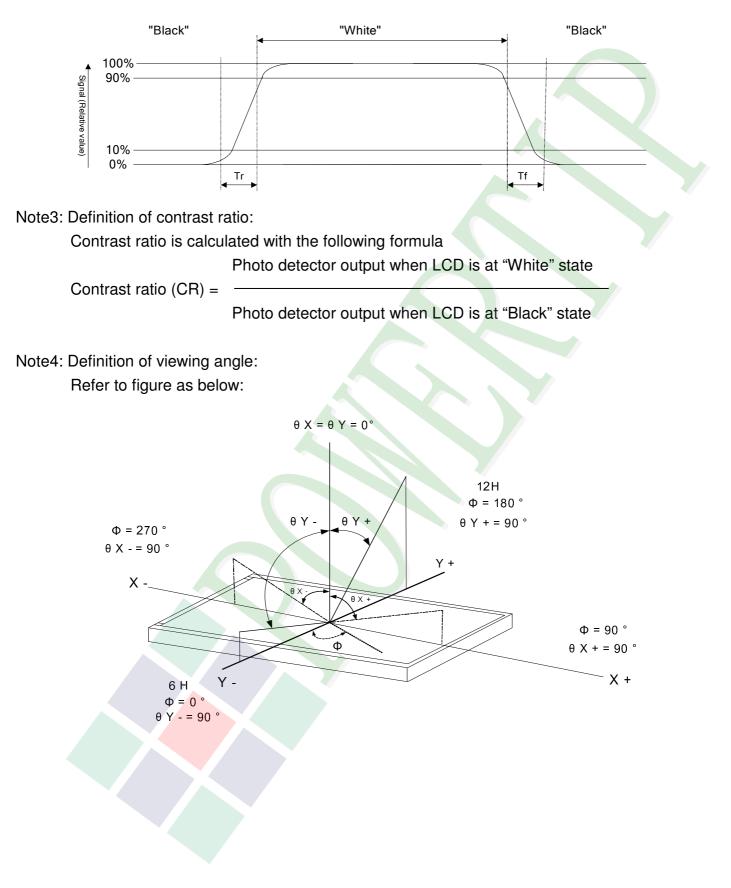
Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.





Normally Black





## **1.6 Backlight Characteristics**

#### **Maximum Ratings**

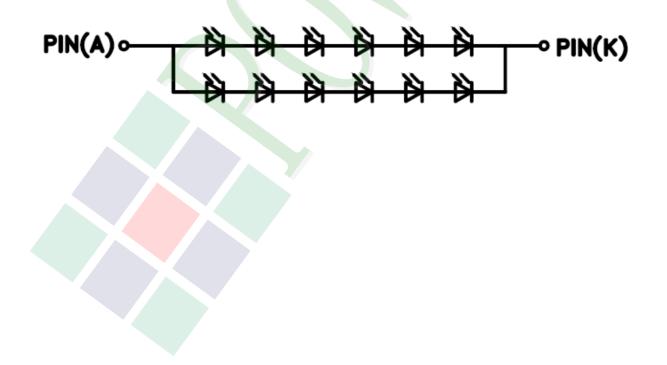
Item	Symbol	Min.	Max.	Unit	Remark
LED Forward Current	lF	3	0	mA	
LED Reverse Voltage	VR	ţ	5	V	One LED
Power Dissipation	PD	12	24	mW	

#### Electrical / Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
Forward Voltage	VF	IF=40mA	17.6	19.2	20.4	V	Note1
LED Life Time	-		50000		1	hr	Note2
Color		White					

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25  $^{\circ}$ C.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25 ℃ and I∟=40 mA. The LED life time could be decreased if operating I∟ is larger than 40 mA.





## 1.7 Touch Panel Characteristics

#### **Features**

Item	Standard Value					
Touch Panel Size	4.3"					
Touch type	Projective Capacitive Touch Panel					
Input Method	Finger / 5 Points Touch					
Interface	l <sup>2</sup> C					
IC	HYCON4635					
I <sup>2</sup> C Address	0x38					

#### I<sup>2</sup>C Address

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	1	1	1	0	0	0	R/W
Bit 0: 0	for Write /	1 for Read					

#### Mechanical Specifications

Item	Standard Value	Unit
Active Area	98.1 (W) * 56.9 (L)	mm
Number of Sensing Channel	18 * 10	

#### Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Supply Voltage	TPVDD	-	-0.3	+6.0	V
Operating Temperature	Тор	-	-20	+70	°C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	°C

## **DC Electrical Characteristics**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	TPVDD	-	-	3.3	-	V

## Touch Panel IC Read/Write description & Register Mapping

Reference : HYCON Touch Driver Porting Reference Guide.



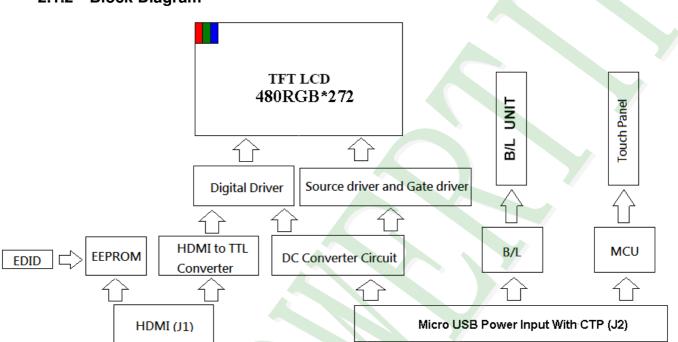
# 2. MODULE STRUCTURE

## 2.1 Counter Drawing

#### 2.1.1 LCM Mechanical Diagram

\* See Appendix

#### 2.1.2 Block Diagram





# 2.2 Interface Pin Description

#### 2.2.1 (J1:HDMI 1.3 A type Interface)

Pin#	Name	Description
1	TX2+	TMDS Data 2+
2	TX2 Shield	TMDS Data 2 Shield
3	TX2–	TMDS Data 2-
4	TX1+	TMDS Data 1+
5	TX1 Shield	TMDS Data 1 Shield
6	TX1–	TMDS Data 1-
7	TX0+	TMDS Data 0+
8	TX0 Shield	TMDS Data 0 Shield
9	TX0–	TMDS Data 0-
10	TXC+	TMDS Clock+
11	TXC Shield	TMDS Clock Shield
12	TXC–	TMDS Clock-
13	CEC	CEC
14	NC	No connection
15	SCL	Serial Clock for DDC
16	SDA	Serial Data for DDC
17	GND	Power ground
18	V5V	+5V Power
19	Hot Plug Detect	Hot Plug Detect



## 2.2.2 (J2:Micro USB Power Input & Capacitive Touch Panel Interface)

Pin#	Name	Description
1	VBus	VBus 4.4V-5.25V
2	D-	Data-
3	D+	Data+
4	ID	No connection
5	GND	Power ground.



## 2.3 HDMI Characteristics

#### 2.3.1 Signal DC&AC Characteristics

#### DC ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT
VID	Analog input differential voltage <sup>(1)</sup>		75	1200	mV
VIC	Analog input common-mode voltage <sup>(1)</sup>		$AV_{DD} - 300$	AV <sub>DD</sub> – 37	mV
V <sub>I(OC)</sub>	Open-circuit analog input voltage		$AV_{DD} - 10$	AV <sub>DD</sub> + 10	mV
I <sub>DD(2PIX)</sub>	Normal 2-pix/clock power supply current (2)	ODCK = 82.5 MHz, 2-pix/clock		370	mA
I <sub>PD</sub>	Power-down current (3)	PD = low		10	mA
I <sub>PDO</sub>	Output drive power-down current <sup>(3)</sup>	PDO = low		35	mA

Specified as dc characteristic with no overshoot or undershoot (1)

(2)Alternating 2-pixel black/2-pixel white pattern. ST = high,  $\overline{STAG}$  = high, QE[23:0] and QO[23:0] C<sub>L</sub> = 10 pF.

Analog inputs are open circuit (transmitter is disconnected from TFP401/401A). (3)

#### AC ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP I	MAX	UNIT
V <sub>ID(2)</sub>	Differential input sensitivity <sup>(1)</sup>		150	1	1560	mV <sub>p-p</sub>
t <sub>ps</sub>	Analog input intra-pair (+ to –) differential skew <sup>(2)</sup>				0.4	t <sub>bit</sub> <sup>(3)</sup>
t <sub>ccs</sub>	Analog input inter-pair or channel-to-channel skew (2)				1	t <sub>pix</sub> (4)
t <sub>ijit</sub>	Worst-case differential input clock jitter tolerance <sup>(2)(5)</sup>		50			ps
+	Fall time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF	2.4			
<b>t</b> <sub>f1</sub>	Pair time of data and control signals (577)	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
	Rise time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	ns
<b>Ļ</b> 1	Rise time of data and control signals (A)	ST = high, C <sub>L</sub> = 10 pF			1.9	115
t <sub>r2</sub>	Rise time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	
	Rise time of ODCK dock**	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
	Fall time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	
t <sub>f2</sub>		ST = high, C <sub>L</sub> = 10 pF			1.9	ns
		1 pixel/clock, PIXS = low, OCK_INV = low	1.8			
t <sub>su1</sub>	Setup time, data and control signal to falling edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	3.8			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	0.7			
		1 pixel/clock, PIXS = low, OCK_INV = low	0.6			
t <sub>h1</sub>	Hold time, data and control signal to falling edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	2.5	2.5		ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	2.9			

(1) Specified as ac parameter to include sensitivity to overshoot, undershoot and reflection.

(2) By characterization

(3)

t<sub>bit</sub> is 1/10 the pixel time, t<sub>pix</sub> t<sub>pix</sub> is the pixel time defined as the period of the RxC input clock. The period of ODCK is equal to t<sub>pix</sub> in 1-pixel/clock mode or 2t<sub>pix</sub> when in 2-pixel/clock mode. (4)

Measured differentially at 50% crossing using ODCK output clock as trigger (5)

Rise and fall times measured as time between 20% and 80% of signal amplitude. (6)

(7)Data and control signals are QE[23:0], QO[23:0], DE, HSYNC, VSYNC. and CTL[3:1].



#### AC ELECTRICAL CHARACTERISTICS (continued)

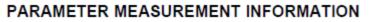
over recommended operating free-air temperature range (unless otherwise noted)

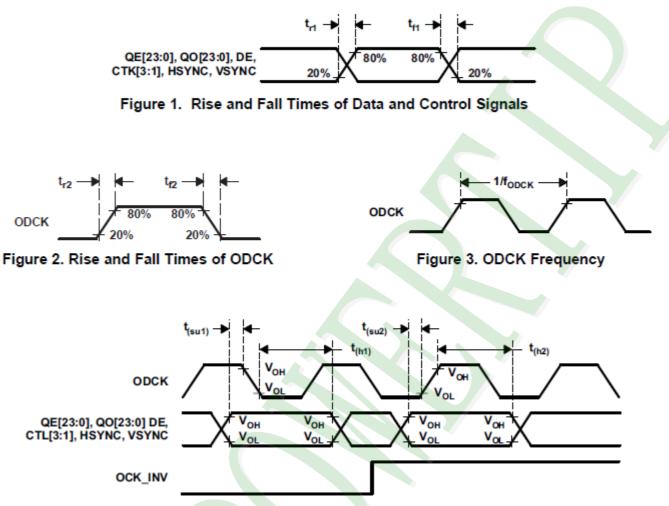
	minerated operating nee an temperature range (	· · · · · · · · · · · · · · · · · · ·				
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		1 pixel/clock, PIXS = low, OCK_INV = high	2.1			
t <sub>su2</sub>	Setup time, data and control signal to rising edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	4			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	1.5			
		1 pixel/clock, PIXS = low, OCK_INV = high	0.5			
t <sub>h2</sub>	Hold time, data and control signal to rising edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	2.4			ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	2.1			
	ODCK fraguanay	PIX = low (1-PIX/CLK)	25		165	MHz
fodck	ODCK frequency	PIX = high (2-PIX/CLK)	12.5		82.5	MHZ
	ODCK duty-cycle		40%	50%	60%	
t <sub>pd(PDL)</sub>	Propagation delay time from PD low to Hi-Z outputs				9	ns
t <sub>pd(PDOL)</sub>	Propagation delay time from PDO low to Hi-Z outputs				9	ns
t <sub>t(HSC)</sub>	Transition time between DE transition to SCDT $\ensuremath{low^{(8)}}$			1e6		t <sub>pix</sub>
t <sub>t(FSC)</sub>	Transition time between DE transition to SCDT high <sup>(8)</sup>			1600		t <sub>pix</sub>
t <sub>d(st)</sub>	Delay time, ODCK latching edge to QE[23:0] data output	STAG = low, PIXS = high		0.25		t <sub>pix</sub>

(8) Link active or inactive is determined by amount of time detected between DE transitions. SCDT indicates link activity.



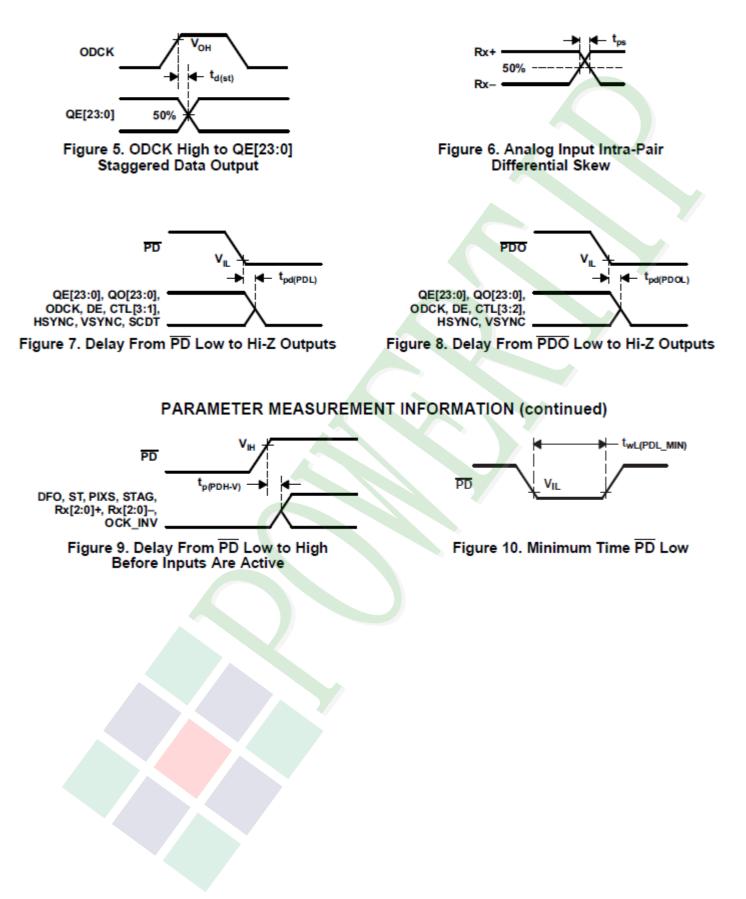
#### 2.3.2 Parameter Measurement Information



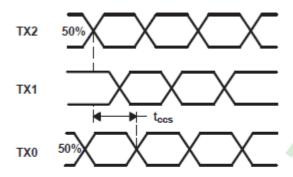


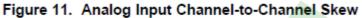
#### Figure 4. Data Setup and Hold Times to Rising and Falling Edges of ODCK











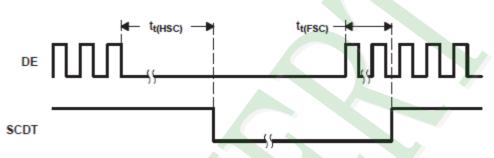


Figure 12. Time Between DE Transitions to SCDT Low and SCDT High

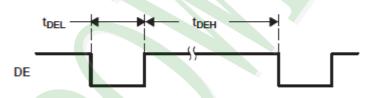
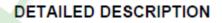
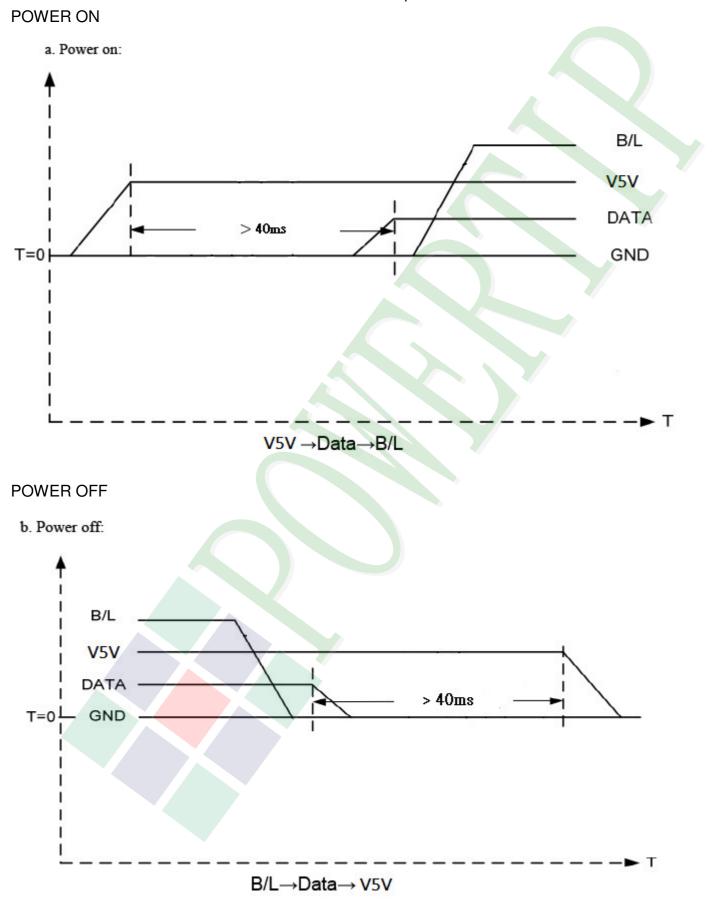


Figure 13. Minimum DE Low and Maximum DE High





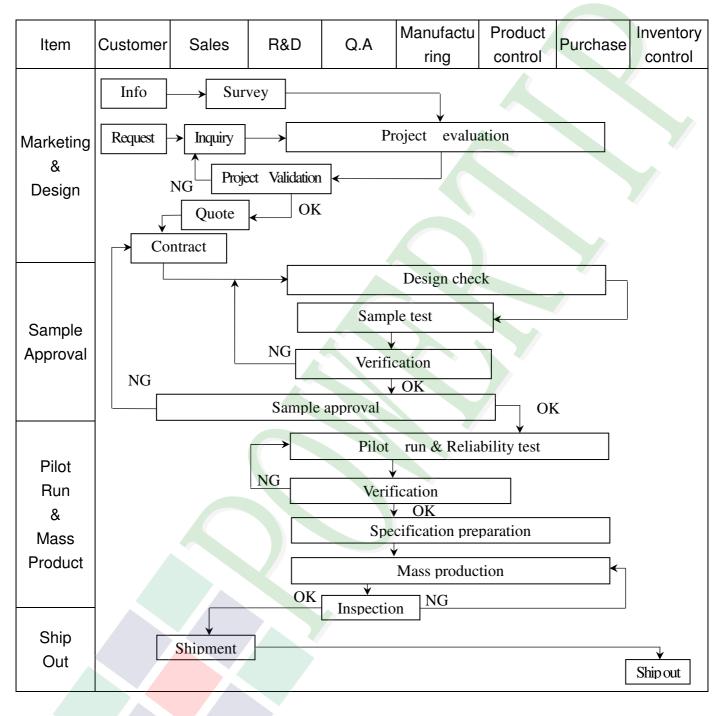
2.3.3 Power Sequence





# **3. QUALITY ASSURANCE SYSTEM**

# 3.1 Quality Assurance Flow Chart



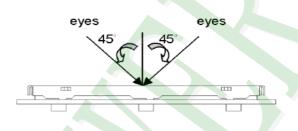


Item	Customer	Sales	R&D	Q.A	Manufact uring	Product control	Purchase	Inventory control
Sales Service	Info	→ Claim sis report	[	Trackin	Failure an Corrective			
Q.A Activity	<ol> <li>ISO 9001 Maintenance Activities</li> <li>Equipment calibration</li> <li>Standardization Management</li> <li>Process improvement proposal</li> <li>Education And Training Activities</li> </ol>							

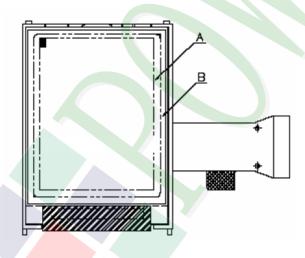
# **POWERTIP**

## **3.2. Inspection Specification**

- Scope : The document shall be applied to TFT-LCD Module for 3. 5" ~10" (Ver.B01).
- ◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level : Major Defect AQL : 0.4 ; Minor Defect AQL : 1.5
- ♦OUT Going Defect Level : Sampling.
- ◆Standard of the product appearance test :
  - a. Manner of appearance test :
  - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
  - (2). The test direction is base on about around  $45^{\circ}$  of vertical line.



#### (3). Definition of area.



A area : viewing area

**B** area : Outside of viewing area

(4). Standard of inspection : (Unit : mm)



#### ◆Specification For TFT-LCD Module 3. 5″~10″:

♦Spe	cification For TFT-L	CD Module 3. 5″~10″:	(Ver.B01)			
NO	Item	Criterion				
		1. 1The part number is inconsistent with work order of production.				
01	Product condition	1. 2 Mixed product types.	Major			
		1. 3 Assembled in inverse direction.	Major			
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major			
03	Outline dimension	3.1 Product dimension and structure must conform to structure diagram.	Major			
	Electrical Testing	4. 1 Missing line character and icon.	Major			
		4. 2 No function or no display.				
04		4. 3 Display malfunction.				
		4. 4 LCD viewing angle defect.				
		4. 5 Current consumption exceeds product specifications.	Major			
		Item Acceptance (Q'ty)				
	Dot defect	Bright Dot ≤ 4				
	Dot delect	<b>Dot</b> Dark Dot $\leq 5$				
	(Bright dot 、	Defect Joint Dot ≤ 3				
05	Dark dot)	<b>Total</b> $\leq 7$	Minor			
	On -display	<ul> <li>5. 1 Inspection pattern : full white , full black , Red , Green and blue screens.</li> <li>5. 2 It is defined as dot defect if defect area &gt;1/2 dot.</li> </ul>				
		5. 3 The distance between two dot defect $\geq 5$ mm.				



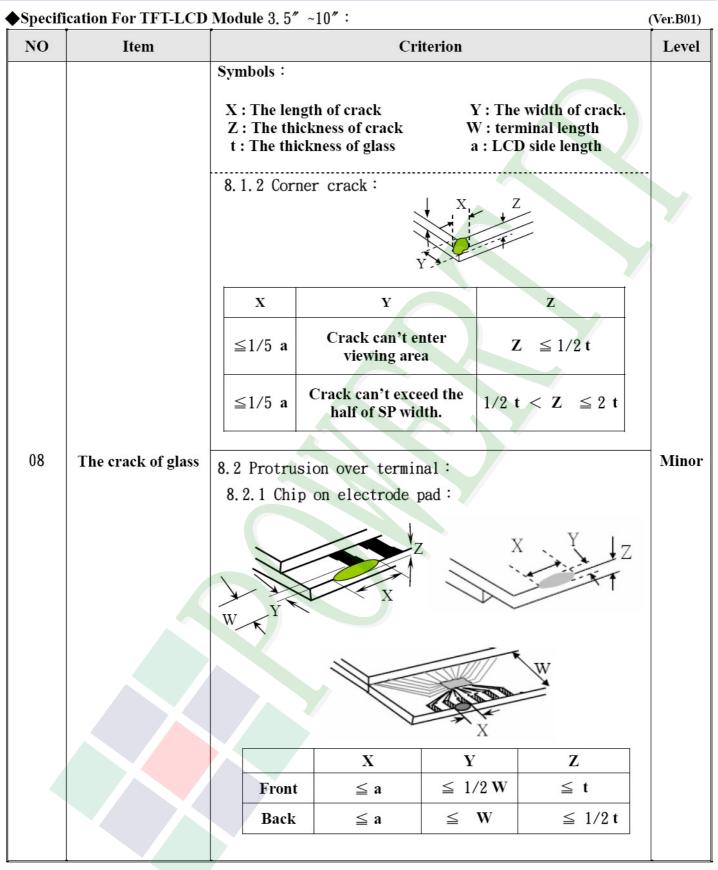
<b>♦</b> Speci	fication For TFT-L	CD Module 3. 5″~10″:	(Ver.B01)
NO	Item	Criterion	Level
		6. 1 Round type ( Non-display or display) :	
		Dimension (diameter : Φ)Acceptance (Q'ty)A areaB area	
	Black or white dot、scratch、	$\Phi \leq 0.25$ Ignore	
	contamination	$0.25 < \Phi \leq 0.50$ 5	
	Round type	$\Phi > 0.50 \qquad 0 \qquad \text{Ignore}$	
	$ _{X} _{Y} $	Total 5	
06	$\Phi = (x+y)/2$	6. 2 Line type( Non-display or display) :	Minor
		Length (L)Width (W)Acceptance (Q'ty)	
	Line type	A area     B area        W ≤ 0.03     Ignore	
		$L \le 10.0 \qquad 0.03 < W \le 0.05 \qquad 4$	
	L	L $\leq$ 5.0 0.05 < W $\leq$ 0.10 2 Ignore	
		W >0.10 As round type	
		Total 5	
		Dimension (diameter : Φ)Acceptance (Q'ty)A areaB area	
		$\Phi \leq 0.25$ Ignore	
07	Polarizer	$0.25 < \Phi \leq 0.50$ 4	Minor
	Bubble	$0.50 < \Phi \leq 0.80$ 1 Ignore	
		$\Phi > 0.80$ 0	
		Total 5	



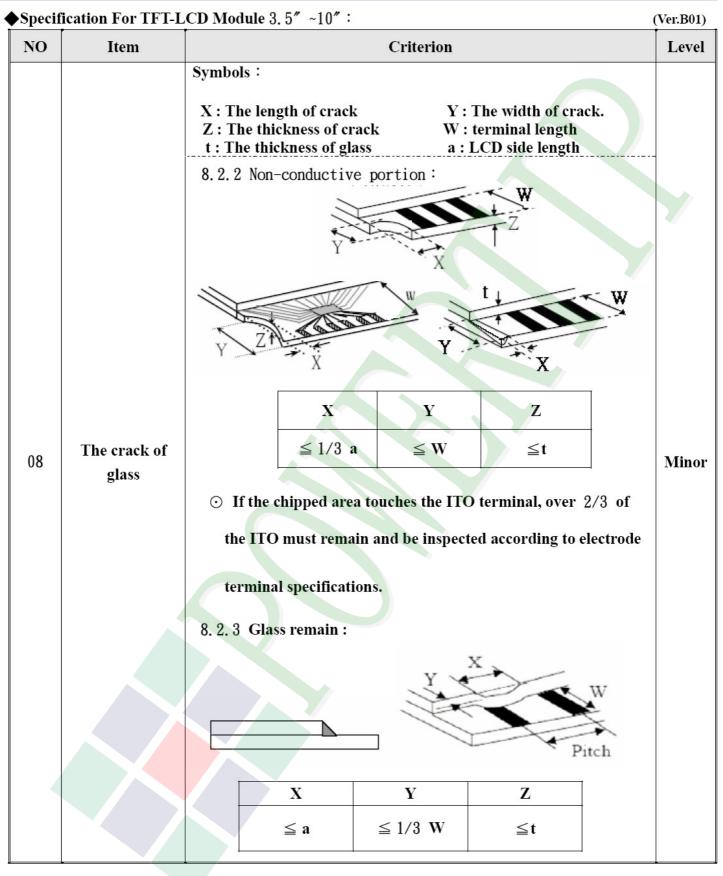
#### ◆Specification For TFT-LCD Module 3. 5″ ~10″:

◆Specification For TFT-LCD Module 3. 5″~10″: (Ver.B01)						
NO	Item	Criterion		Level		
		Z : The thickness of crack V	Y : The width of crack. V : terminal length a : LCD side length			
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	ick between panels:			
		Y Z Z	X X X			
08	The crack of glass	SP Y (OK)	ING]	Minor		
		Seal width	Y			
		XY	z			
		≤ a Crack can't enter viewing area	$\leq 1/2 t$			
		$\leq a \qquad \begin{array}{c} Crack can't exceed the \\ half of SP width. \end{array}$	$1/2 t < Z \leq t$			











# 4. RELIABILITY TEST

## 4.1 Reliability Test Condition

(Ver.B01)

	Reliability lest Condition (ver.BUI)				
NO.	<b>TEST ITEM</b>	TEST CONDITION			
1	High Temperature Storage Test	Keep in +80 ±2°C 240 hrs			
2	Low Temperature Storage Test	Keep in −30 ±2°C 240 hrs			
3	High Temperature / High Humidity Storage Test	Keep in +60 °C / 90% R.H duration for 240 hrs (Excluding the polarizer)			
4	Temperature Cycling Storage Test	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$			
5	ESD Test	Air Discharge:Contact Discharge:Apply 2 KV with 5 timesApply 250 V with 5 timesDischarge for each polarity +/-discharge for each polarity +/-1. Temperature ambiance : 15°C ~35°C2. Humidity relative : 30% ~60%3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%4. Discharge Resistance(Rd) : 330Ω±10%5. Discharge, mode of operation :Single Discharge (time between successive discharges at least 1 sec)(Tolerance if the output voltage indication : ±5%)			
6	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min/sweep)</li> <li>The amplitude of vibration :1.5 mm</li> <li>Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ol>			
7	Drop Test (Packaged)	Packing Weight (Kg 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454 Drop Direction : %1 corner / 3 edg	122       76       61       46		

**OResult Evaluation Criteria :** 

Under the display quality test conditions with normal operations with normal operation state. Do not change these conditions as such changes may affect practical display function.

(Normal operation state)

Temperature: +20~30 °C Humidity: 50~70% Atmospheric pressure: 86~106Kpa



# **5. PRECAUTION RELATING PRODUCT HANDLING**

# 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

# 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

# 5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}C \pm 5^{\circ}C$  and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

# 5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

